

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 21 (currently amended): A method for making a one component heat curable epoxy resin system, comprising the step of mixing together components (A), (B), (C), and (E):

(A) an epoxy resin or compound containing more than one epoxy group;

(B) an amine solidifying system present in insufficient quantities to cause gelation after the amino hydrogen atoms are consumed by epoxy groups, under the reaction conditions chosen for (A) and (B), and which yields a product with a Kofler Heat Bank melting point of less than 55°C;

(C) a latent hardener system for (A) and the reaction product of (A) and (B), wherein (C) is different from (B) and remains sufficiently unreacted under the conditions of reaction for (A) and (B) such that the one component heat curable epoxy resin system has a tack life of at least 6 months at room temperature; and

(E) an expanding agent;

in such a way that (A) and (B) react to completion at room temperature over a period of between 2-14 days; and wherein the reaction product of (A) and (B) has melting point stability of at least six months at normal workshop temperatures.

Claim 22 (previously presented): A method according to claim 21, wherein the mixing of the composition is carried out batchwise or continuously.

Claim 23 (previously presented): A method according to claim 21, wherein the mixed composition and the shape and size of container ensure that the excess heat generated does not increase the temperature of the composition to a point to cause (C) or (E) to substantially react.

Claim 24 (previously presented): A method according to claim 21, wherein the mixing step is carried out in the resin system's final container.

Claim 25 (previously presented): A method according to claim 21, wherein the partially solidified mixture is heated to speed completion of the solidification reaction of (A) and (B) provided the temperature chosen or the temperature reached due to the completion of the solidification reaction does not cause (C) or (E) to substantially react.

Claim 26 (previously presented): A method according to claim 21, wherein a majority of the epoxy groups are glycidyl ether, glycidyl amine, glycidyl ester, and/or cycloaliphatic glycidyl groups.

Claim 27 (previously presented): A method according to claim 21, wherein the epoxy resin or compound, individually or as a mixture, is a free flowing liquid at 80°C or below.

Claim 28 (previously presented): A method according to claim 21, wherein the amine solidifying system comprises aromatic, cycloaliphatic or dicyclic primary amines, secondary amines or mixtures thereof and optionally acid accelerators.

Claim 29 (previously presented): A method according to claim 21, wherein the amine solidifying system comprises a majority of difunctional amines.

Claim 30 (previously presented): A method according to claim 21, wherein the hardener system (C) is selected from the group consisting of 4,4'-diaminodiphenyl sulphone, boron trifluoride amine complexes, latent imidazoles, polycarboxylic acids, polyhydrazides, dicyandiamide, latent epoxy amine adducts and substituted ureas.

Claim 31 (previously presented): A method according to claim 21, wherein expanding agent (E) is an agent that generates gases by chemical decomposition or by boiling of liquids or expansion of gases contained within expandable shells.

Claim 32 (previously presented): A one component heat curable epoxy resin system, obtained by mixing together components (A) and (B) in the presence of components (C) and (E) wherein

- (A) is an epoxy resin or compound containing more than one epoxy group;
- (B) is an amine solidifying system present in insufficient quantities to cause gelation after the amino hydrogen atoms are consumed by epoxy groups, under the reaction conditions chosen for (A) and (B), and which yields a product with a Kofler Heat Bank melting point of less than 55°C;
- (C) is a latent hardener system for (A) and the reaction product of (A) and (B), wherein (C) is different from (B) and remains unreacted under the conditions of reaction for (A) and (B) such that the one component heat curable epoxy resin system has a tack life of at least 6 months at room temperature; and
- (E) is an expanding agent;
- wherein (A) and (B) react to completion at room temperature over a period of between 2-14 days; wherein the reaction product of (A) and (B) has melting point stability of at least six months at normal workshop temperatures.

Claim 33 (previously presented): A cured product obtained by heating a system according to claim 32.

Claim 35 (previously presented): The method according to claim 21, wherein the amine solidifying system comprises aromatic or cycloaliphatic primary or secondary amines.

Claim 36 (previously presented): The method according to claim 35, wherein the amine solidifying system comprises aromatic primary or secondary amines.